

Product Summary

| BV_{DSS} | $R_{DS(ON)}$ max | I_D max $T_C = +25^\circ C$ |
|------------|---------------------------------|----------------------------------|
| 30V | 5.0m Ω @ $V_{GS} = 10V$ | 60A |
| | 7.4m Ω @ $V_{GS} = 4.5V$ | 50A |

Features and Benefits

- Low $R_{DS(ON)}$ – ensures on state losses are minimized
- Small form factor thermally efficient package enables higher density end products
- Occupies just 33% of the board area occupied by SO-8 enabling smaller end product
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Description and Applications

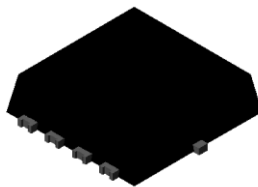
This MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- Power Management Functions
- DC-DC Converters

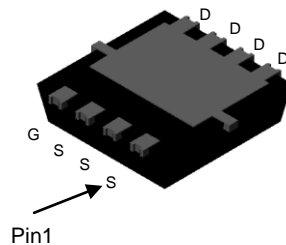
Mechanical Data

- Case: PowerDI[®] 3333-8 (SWP) (Type UX)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish — Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208⁽³⁾
- Weight: 0.072 grams (Approximate)

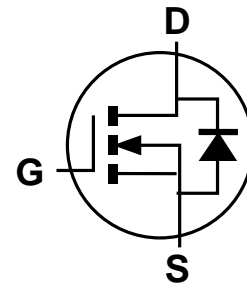
PowerDI3333-8 (SWP) (Type UX)



Top View



Bottom View



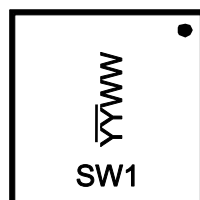
Equivalent Circuit

Ordering Information (Note 4)

| Part Number | Case | Packaging |
|----------------|-------------------------------|-------------------|
| DMN3009LFVW-7 | PowerDI3333-8 (SWP) (Type UX) | 2,000/Tape & Reel |
| DMN3009LFVW-13 | PowerDI3333-8 (SWP) (Type UX) | 3,000/Tape & Reel |

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



SW1 = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Last Two Digit of Year (ex: 17 = 2017)
 WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|---|------------------|------------------------|------|
| Drain-Source Voltage | V _{DSS} | 30 | V |
| Gate-Source Voltage | V _{GSS} | ±20 | V |
| Continuous Drain Current (Note 7) V _{GS} = 10V | I _D | T _C = +25°C | 60 |
| | | T _C = +70°C | 48 |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%) | I _{DM} | 90 | A |
| Maximum Continuous Body Diode Forward Current (Note 7) | I _S | 60 | A |
| Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%) | I _{SM} | 90 | A |
| Avalanche Current, L = 0.1mH (Note 8) | I _{AS} | 33 | A |
| Avalanche Energy, L = 0.1mH (Note 8) | E _{AS} | 58 | mJ |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|--|-----------------------------------|------------------|------|
| Total Power Dissipation (Note 5) | P _D | 1.0 | W |
| Thermal Resistance, Junction to Ambient (Note 5) | R _{θJA} | Steady State | 126 |
| Total Power Dissipation (Note 6) | | P _D | 2.0 |
| Thermal Resistance, Junction to Ambient (Note 6) | R _{θJA} | Steady State | 62 |
| Thermal Resistance, Junction to Case (Note 7) | | R _{θJC} | 4.6 |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|--|---------------------|-----|-------|------|------|--|
| OFF CHARACTERISTICS (Note 9) | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 30 | — | — | V | V _{GS} = 0V, I _D = 250µA |
| Zero Gate Voltage Drain Current | I _{DSS} | — | — | 1 | µA | V _{DS} = 24V, V _{GS} = 0V |
| Gate-Source Leakage | I _{GSS} | — | — | ±100 | nA | V _{GS} = ±20V, V _{DS} = 0V |
| ON CHARACTERISTICS (Note 9) | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | 1 | — | 2.5 | V | V _{DS} = V _{GS} , I _D = 250µA |
| Static Drain-Source On-Resistance | R _{DS(ON)} | — | 3.5 | 5.0 | mΩ | V _{GS} = 10V, I _D = 30A |
| | | — | 4.9 | 7.4 | | V _{GS} = 4.5V, I _D = 15A |
| Diode Forward Voltage | V _{SD} | — | 0.7 | 1.2 | V | V _{GS} = 0V, I _S = 1A |
| DYNAMIC CHARACTERISTICS (Note 10) | | | | | | |
| Input Capacitance | C _{iss} | — | 2,000 | — | pF | V _{DS} = 15V, V _{GS} = 0V, f = 1MHz |
| Output Capacitance | C _{oss} | — | 315 | — | pF | |
| Reverse Transfer Capacitance | C _{rss} | — | 247 | — | pF | |
| Gate Resistance | R _g | — | 2.2 | — | Ω | V _{DS} = 0V, V _{GS} = 0V, f = 1MHz |
| Total Gate Charge (V _{GS} = 4.5V) | Q _g | — | 20 | — | nC | V _{DS} = 15V, I _D = 15A |
| Total Gate Charge (V _{GS} = 10V) | Q _g | — | 42 | — | nC | |
| Gate-Source Charge | Q _{gs} | — | 4.7 | — | nC | |
| Gate-Drain Charge | Q _{gd} | — | 7.4 | — | nC | |
| Turn-On Delay Time | t _{D(ON)} | — | 3.9 | — | ns | V _{DD} = 15V, V _{GS} = 10V, R _G = 3.3Ω, I _D = 15A |
| Turn-On Rise Time | t _R | — | 4.1 | — | ns | |
| Turn-Off Delay Time | t _{D(OFF)} | — | 31 | — | ns | |
| Turn-Off Fall Time | t _F | — | 15 | — | ns | |
| Body Diode Reverse Recovery Time | t _{RR} | — | 15 | — | ns | I _F = 15A, di/dt = 100A/µs |
| Body Diode Reverse Recovery Charge | Q _{RR} | — | 6.0 | — | nC | |

- Notes:
- Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
 - Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.
 - Thermal resistance from junction to soldering point (on the exposed drain pad).
 - I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to product testing.

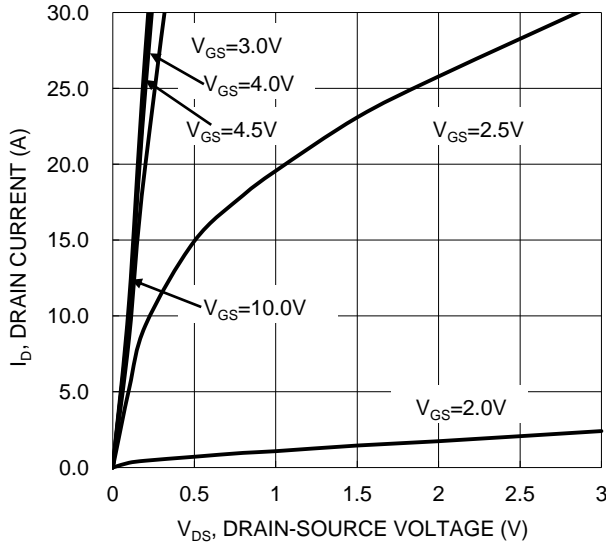


Figure 1. Typical Output Characteristic

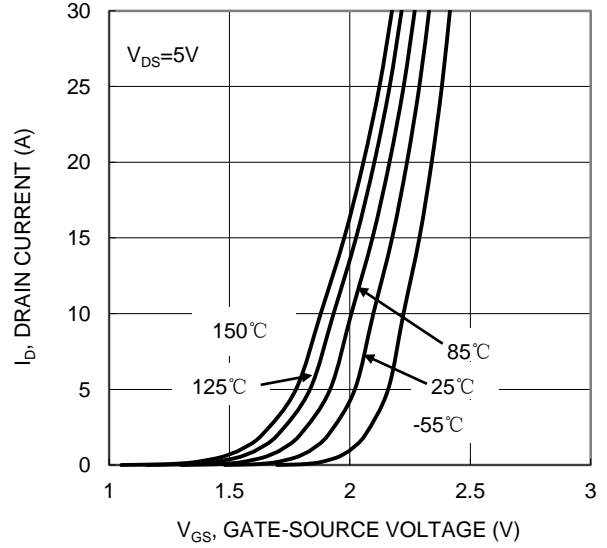


Figure 2. Typical Transfer Characteristic

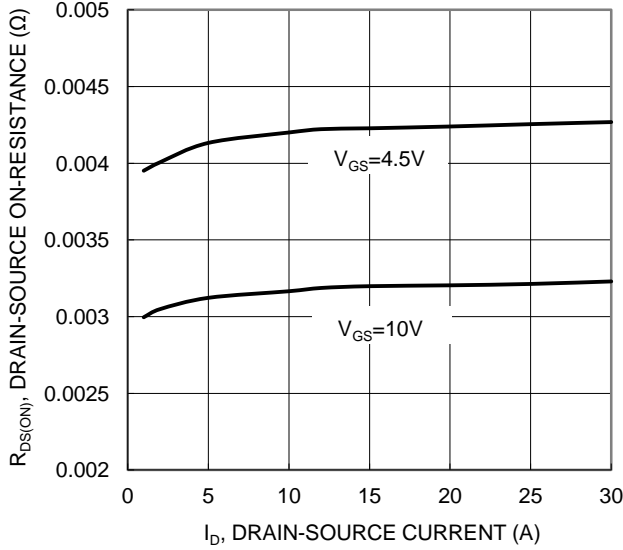


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

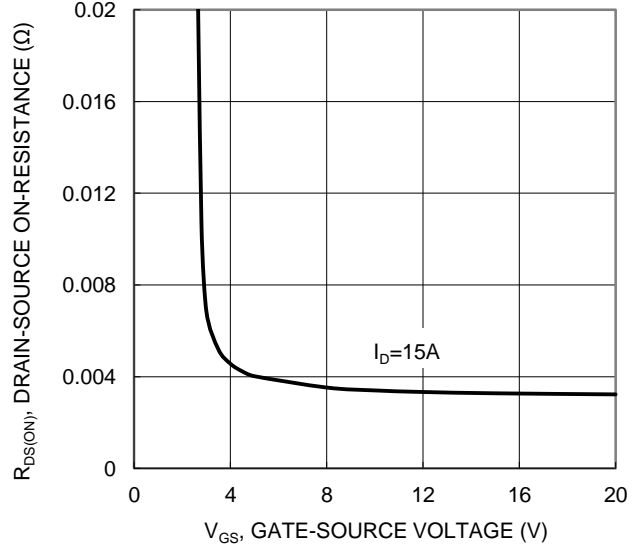


Figure 4. Typical Transfer Characteristic

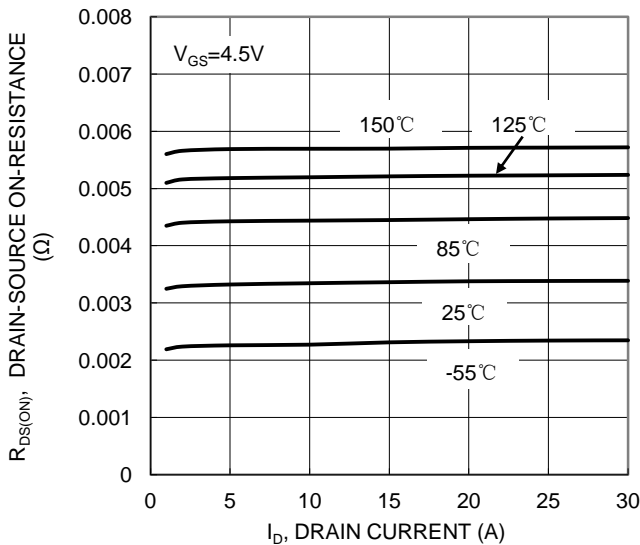


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

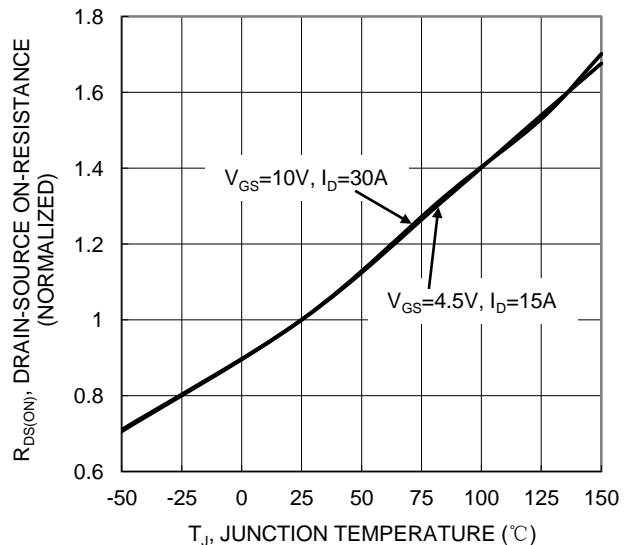


Figure 6. On-Resistance Variation with Temperature

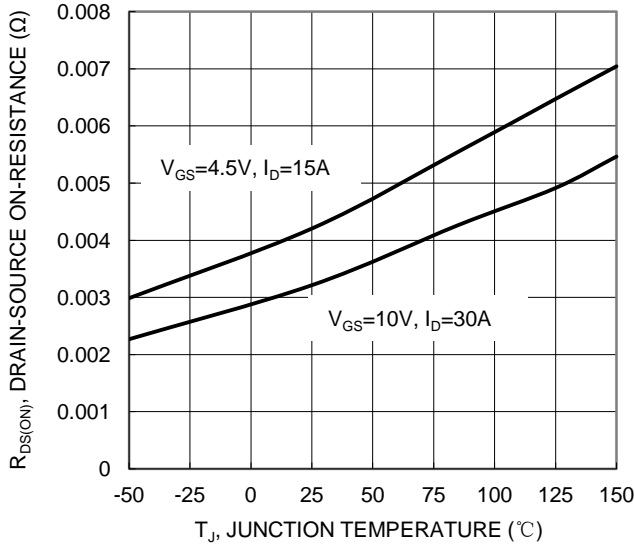


Figure 7. On-Resistance Variation with Temperature

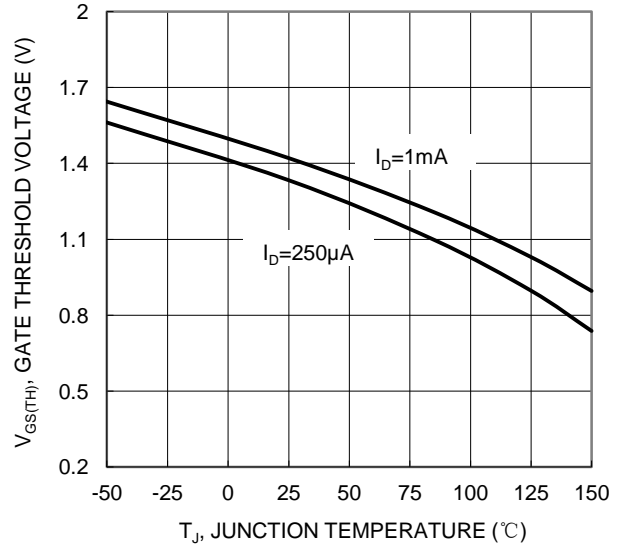


Figure 8. Gate Threshold Variation vs. Junction Temperature

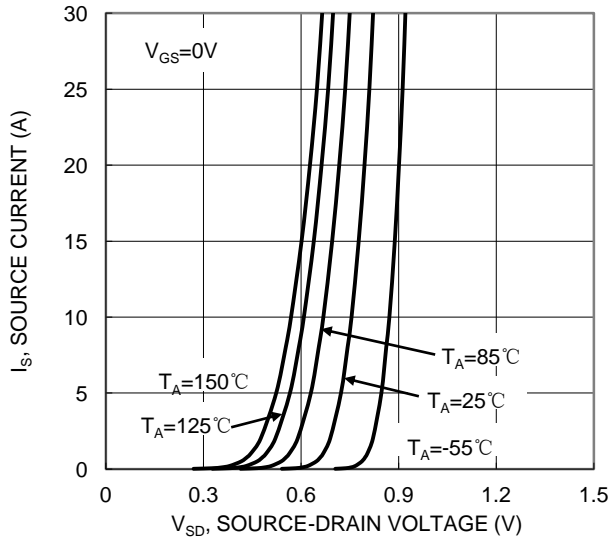


Figure 9. Diode Forward Voltage vs. Current

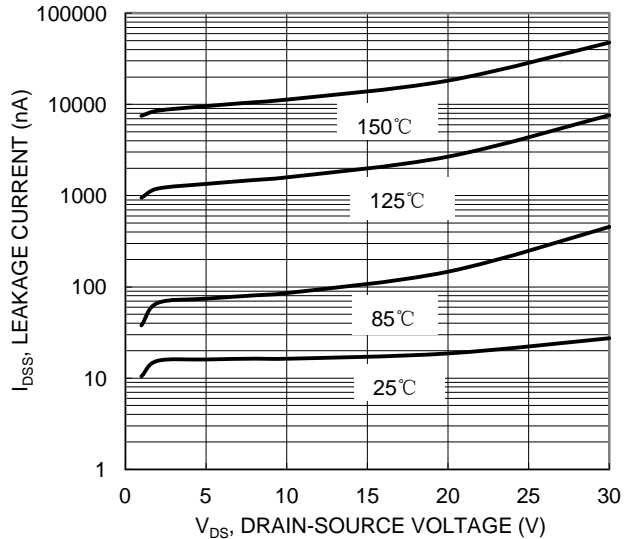


Figure 10. Typical Drain-Source Leakage Current vs. Voltage

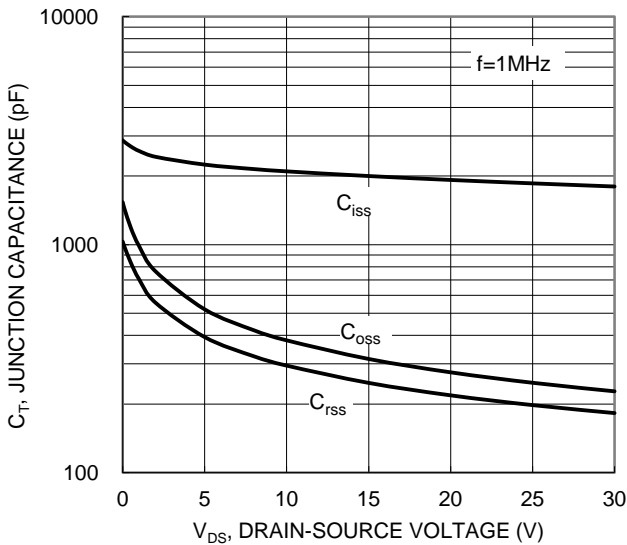


Figure 11. Typical Junction Capacitance

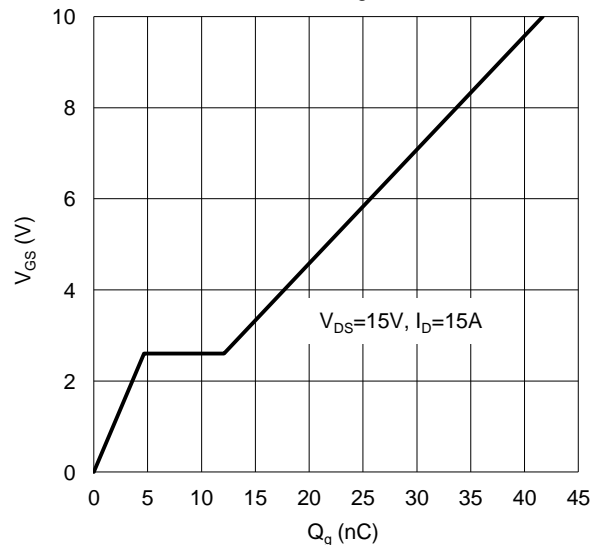
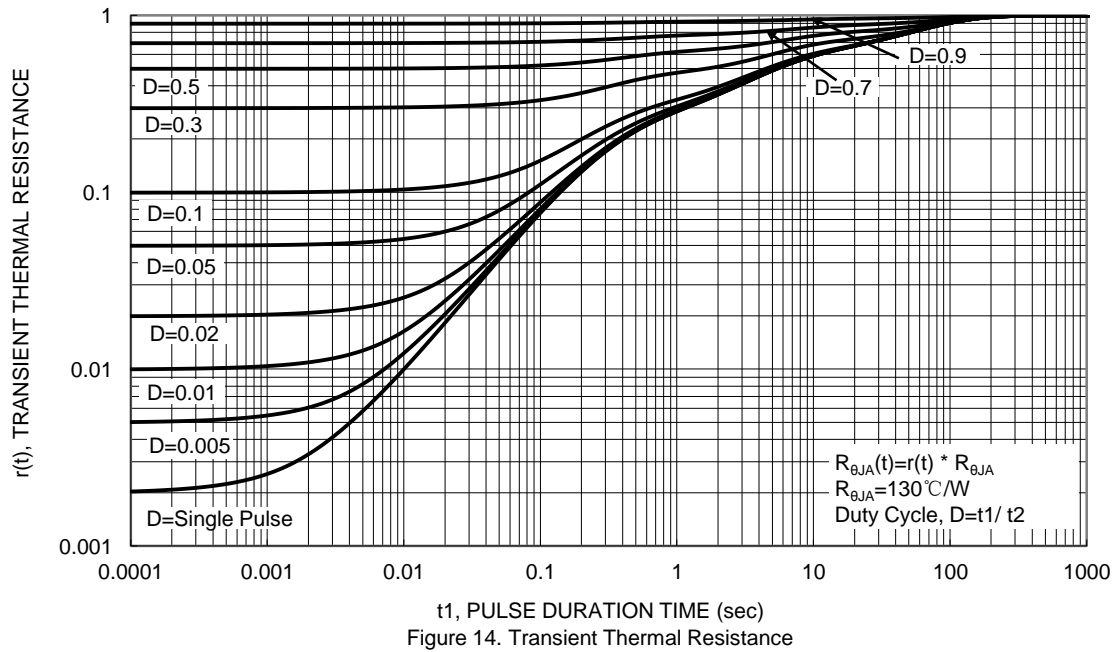
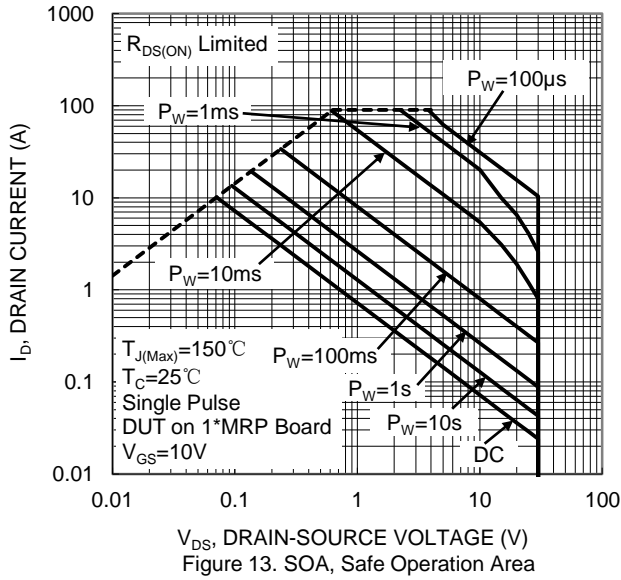


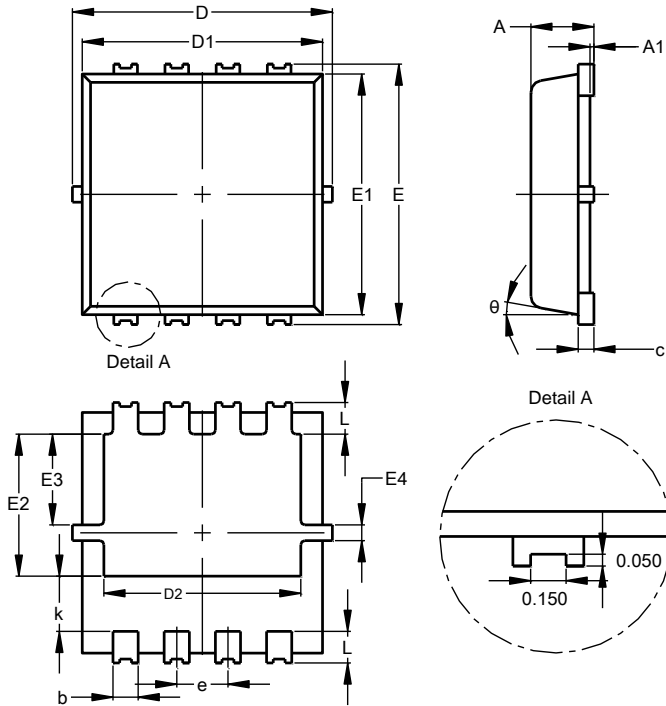
Figure 12. Gate Charge



Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI3333-8 (SWP) (Type UX)

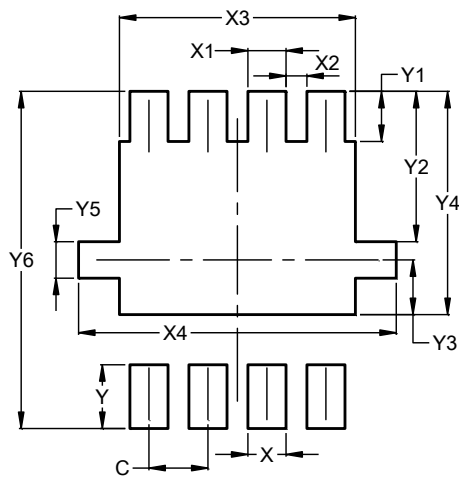


| PowerDI3333-8 (SWP) (Type UX) | | | |
|----------------------------------|------|------|------|
| Dim | Min | Max | Typ |
| A | 0.75 | 0.85 | 0.80 |
| A1 | 0.00 | 0.05 | -- |
| b | 0.25 | 0.40 | 0.32 |
| c | 0.10 | 0.25 | 0.15 |
| D | 3.20 | 3.40 | 3.30 |
| D1 | 2.95 | 3.15 | 3.05 |
| D2 | 2.30 | 2.70 | 2.50 |
| E | 3.20 | 3.40 | 3.30 |
| E1 | 2.95 | 3.15 | 3.05 |
| E2 | 1.60 | 2.00 | 1.80 |
| E3 | 0.95 | 1.35 | 1.15 |
| E4 | 0.10 | 0.30 | 0.20 |
| e | -- | -- | 0.65 |
| k | 0.50 | 0.90 | 0.70 |
| L | 0.30 | 0.50 | 0.40 |
| θ | 0° | 12° | 10° |
| All Dimensions in mm | | | |

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI3333-8 (SWP) (Type UX)



| Dimensions | Value (in mm) |
|------------|---------------|
| C | 0.650 |
| X | 0.420 |
| X1 | 0.420 |
| X2 | 0.230 |
| X3 | 2.600 |
| X4 | 3.500 |
| Y | 0.700 |
| Y1 | 0.550 |
| Y2 | 1.650 |
| Y3 | 0.600 |
| Y4 | 2.450 |
| Y5 | 0.400 |
| Y6 | 3.700 |

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